Package Outline Drawing
W11x11.121B
121 BALL WAFER LEVEL CHIP SCALE PACKAGE (WLCSP 0.5mm pitch)
Rev 0, 2/14

NOTES:
1. All dimensions are in millimeters.
2. Dimensions and tolerance per ASMEY 14.5M - 1994 and JESD 95-1, SPP-010.
△ NSMD refers to non-solder mask defined pad design per Intersil Techbrief TB451.